

IN THE SPECIFICATION:

Please amend Paragraph [0033] to read as follows:

[0033] A preferred embodiment is characterized in that the abovementioned conveying means is formed so that a free standing period of no operation of shifting the substrates in an interval extending from the abovementioned bonding part to the abovementioned curing part.

Please amend Paragraph [0065] to read as follows:

[0065] The pre-curing standing positions 14a through 14d are positions in which the substrates following bonding are allowed to stand at room temperature in the atmosphere while being conveyed. As a result, the free standing part described in the claims is constructed. Furthermore, the means for setting a rotational speed of the turntable 1 is set so that the correction of warping (described later in Figures 2 and 3) is performed while the bonded substrates move through the pre-curing standing positions 14a through 14d. A curing part not shown in the figures is constructed in the curing position 15. This curing part is a means which cures the adhesive agent by irradiating the bonded substrates with ultraviolet light; any universally known technique may be used. The post-curing standing position 16 is a position in which the substrates following curing of the adhesive agent are allowed to stand at room temperature in the atmosphere while being conveyed. The conveying position 17 is a position where the bonded substrates are conveyed out to the next process.

Please amend Paragraph [0067] to read as follows:

[0067] As the turntable 1 rotates, the pair of facing substrates are conveyed into the bonding part of the bonding position 13, whereupon a vacuum is applied to the vacuum vessel,

and the substrates are bonded to each other. The substrates following bonding are conveyed out from the vacuum vessel into the atmosphere at room temperature by the rotation of the turntable 1, and move through the pre-curing standing positions 14a through 14d, so that these substrates are allowed to stand for a fixed time, thus correcting the warping. When the substrates thus move through the bonding position 13, pre-curing standing positions 14a through 14d, curing position 15, post-curing standing position 16 and conveying position 17, since the substrates or susceptors carrying substrates are carried on the turntable 1, no work such as shifting by other devices or the like is performed. In other words, at least from the bonding part to the standing parts and curing part, the substrates or susceptors carrying substrates are conveyed without any contact with devices other than the conveying means and are free standing on the turntable.